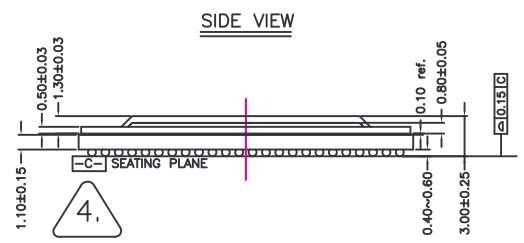
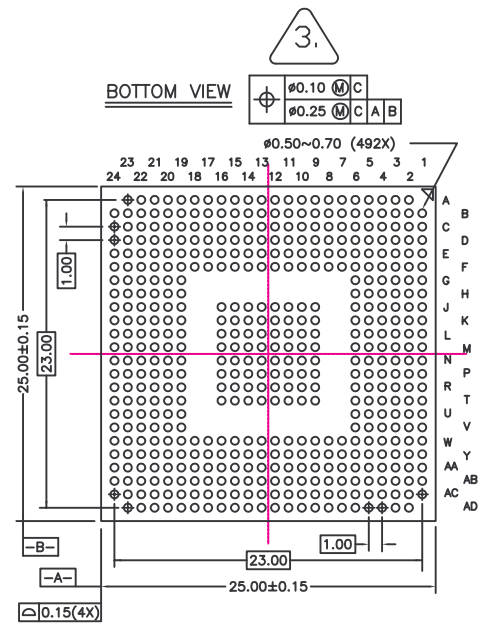
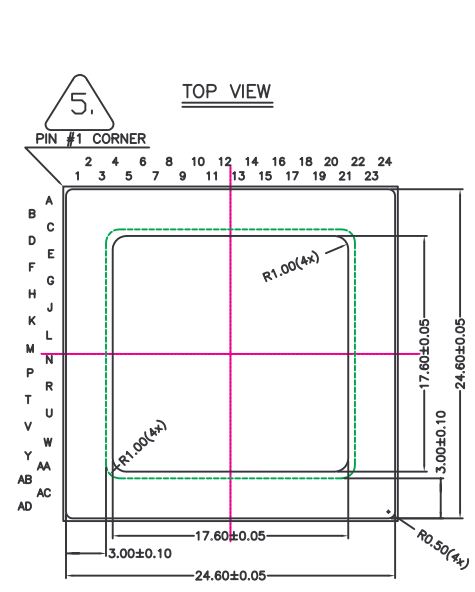



REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	08/08	Eden



NOTES:

1. DIMENSION IS MM.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM AND BALL DIA IS 0.60MM
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. A1 BALL PAD CORNER I.D.

SIGNATURE		DATE		 <p>TITLE: MARKETING OUTLINE DRAWING 25MM X 25MM X 3.00MM, 492 BALLS, HFBGA W/HEAT SINK, 6 LAYER 1.00 MM PITCH</p>			
DOC. CONTROL:							
ENGR. MGR:							
MFG. ENGR:							
CHECKED BY:	Bill Harmon	08/08		SIZE	FSCM NO.	PART NO.	REV.
DRAWN BY:	Eden Chen	08/08		A		21-0435	A
				SCALE	N/A		SHEET 1 of 1